Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	H8/300H
Core Size	16-Bit
Speed	20MHz
Connectivity	SCI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	30
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/df36022gfpv

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

   "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

   "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

   "Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

General Precautions on Handling of Product

1. Treatment of NC Pins

Note: Do not connect anything to the NC pins.
The NC (not connected) pins are either not connected to any of the internal circuitry or are used as test pins or to reduce noise. If something is connected to the NC pins, the operation of the LSI is not guaranteed.

2. Treatment of Unused Input Pins

Note: Fix all unused input pins to high or low level.
Generally, the input pins of CMOS products are high-impedance input pins. If unused pins are in their open states, intermediate levels are induced by noise in the vicinity, a pass-through current flows internally, and a malfunction may occur.

3. Processing before Initialization

Note: When power is first supplied, the product's state is undefined.
The states of internal circuits are undefined until full power is supplied throughout the chip and a low level is input on the reset pin. During the period where the states are undefined, the register settings and the output state of each pin are also undefined. Design your system so that it does not malfunction because of processing while it is in this undefined state. For those products which have a reset function, reset the LSI immediately after the power supply has been turned on.

4. Prohibition of Access to Undefined or Reserved Addresses

Note: Access to undefined or reserved addresses is prohibited.
The undefined or reserved addresses may be used to expand functions, or test registers may have been be allocated to these addresses. Do not access these registers; the system's operation is not guaranteed if they are accessed.

6.2.2 Standby Mode 75
6.2.3 Subsleep Mode 75
6.3 Operating Frequency in Active Mode 76
6.4 Direct Transition 76
6.5 Module Standby Function 76

Section 7 ROM 77
7.1 Block Configuration 78
7.2 Register Descriptions 79
7.2.1 Flash Memory Control Register 1 (FLMCR1) 79
7.2.2 Flash Memory Control Register 2 (FLMCR2) 80
7.2.3 Erase Block Register 1 (EBR1) 81
7.2.4 Flash Memory Enable Register (FENR) 81
7.3 On-Board Programming Modes 82
7.3.1 Boot Mode 82
7.3.2 Programming/Erasing in User Program Mode 85
7.4 Flash Memory Programming/Erasing 86
7.4.1 Program/Program-Verify 86
7.4.2 Erase/Erase-Verify 88
7.4.3 Interrupt Handling when Programming/Erasing Flash Memory 89
7.5 Program/Erase Protection 91
7.5.1 Hardware Protection 91
7.5.2 Software Protection 91
7.5.3 Error Protection 91

Section 8 RAM 93

Section 9 I/O Ports 95
9.1 Port 1 95
9.1.1 Port Mode Register 1 (PMR1) 96
9.1.2 Port Control Register 1 (PCR1) 97
9.1.3 Port Data Register 1 (PDR1) 97
9.1.4 Port Pull-Up Control Register 1 (PUCR1) 98
9.1.5 Pin Functions 98
9.2 Port 2 100
9.2.1 Port Control Register 2 (PCR2) 100
9.2.2 Port Data Register 2 (PDR2) 101
9.2.3 Pin Functions 101
9.3 Port 5 102
9.3.1 Port Mode Register 5 (PMR5) 103

13.4.2 SCI3 Initialization 193
13.4.3 Data Transmission 194
13.4.4 Serial Data Reception 196
13.5 Operation in Clocked Synchronous Mode 200
13.5.1 Clock 200
13.5.2 SCI3 Initialization 201
13.5.3 Serial Data Transmission 201
13.5.4 Serial Data Reception (Clocked Synchronous Mode) 203
13.5.5 Simultaneous Serial Data Transmission and Reception 205
13.6 Multiprocessor Communication Function 207
13.6.1 Multiprocessor Serial Data Transmission 208
13.6.2 Multiprocessor Serial Data Reception 210
13.7 Interrupts 214
13.8 Usage Notes 215
13.8.1 Break Detection and Processing 215
13.8.2 Mark State and Break Sending 215
13.8.3 Receive Error Flags and Transmit Operations (Clocked Synchronous Mode Only) 215
13.8.4 Receive Data Sampling Timing and Reception Margin in Asynchronous Mode 216

Section 14 A/D Converter 217
14.1 Features 217
14.2 Input/Output Pins 219
14.3 Register Description 220
14.3.1 A/D Data Registers A to D (ADDRA to ADDRD) 220
14.3.2 A/D Control/Status Register (ADCSR) 221
14.3.3 A/D Control Register (ADCR) 222
14.4 Operation 223
14.4.1 Single Mode 223
14.4.2 Scan Mode 223
14.4.3 Input Sampling and A/D Conversion Time 224
14.4.4 External Trigger Input Timing 225
14.5 A/D Conversion Accuracy Definitions 226
14.6 Usage Notes 228
14.6.1 Permissible Signal Source Impedance 228
14.6.2 Influences on Absolute Accuracy 228

Table 2.8 System Control Instructions

Instruction	Size*	Function
TRAPA	—	Starts trap-instruction exception handling.
RTE	—	Returns from an exception-handling routine.
SLEEP	—	Causes a transition to a power-down state.
LDC	B/W	(EAs) → CCR Moves the source operand contents to the CCR. The CCR size is one byte, but in transfer from memory, data is read by word access.
STC	B/W	CCR → (EAd), EXR → (EAd) Transfers the CCR contents to a destination location. The condition code register size is one byte, but in transfer to memory, data is written by word access.
ANDC	B	CCR ∧ #IMM → CCR, EXR ∧ #IMM → EXR Logically ANDs the CCR with immediate data.
ORC	B	CCR ∨ #IMM → CCR, EXR ∨ #IMM → EXR Logically ORs the CCR with immediate data.
XORC	B	CCR ⊕ #IMM → CCR, EXR ⊕ #IMM → EXR Logically XORs the CCR with immediate data.
NOP	—	PC + 2 → PC Only increments the program counter.

Note: * Refers to the operand size.
B: Byte
W: Word

10.3.3 Timer Control Register V0 (TCRV0)

TCRV0 selects the input clock signals of TCNTV, specifies the clearing conditions of TCNTV, and controls each interrupt request.

Bit	Bit Name	Initial Value	R/W	Description
7	CMIEB	0	R/W	Compare Match Interrupt Enable B When this bit is set to 1, interrupt request from the CMFB bit in TCSRV is enabled.
6	CMIEA	0	R/W	Compare Match Interrupt Enable A When this bit is set to 1, interrupt request from the CMFA bit in TCSRV is enabled.
5	OVIE	0	R/W	Timer Overflow Interrupt Enable When this bit is set to 1, interrupt request from the OVF bit in TCSRV is enabled.
4	CCLR1	0	R/W	Counter Clear 1 and 0
3	CCLR0	0	R/W	These bits specify the clearing conditions of TCNTV. 00: Clearing is disabled 01: Cleared by compare match A 10: Cleared by compare match B 11: Cleared on the rising edge of the TMRIV pin. The operation of TCNTV after clearing depends on TRGE in TCRV1.
2	CKS2	0	R/W	Clock Select 2 to 0 These bits select clock signals to input to TCNTV and the counting condition in combination with ICKS0 in TCRV1. Refer to table 10.2.
1	CKS1	0	R/W	
0	CKS0	0	R/W	

10.6 Usage Notes

The following types of contention or operation can occur in timer V operation.

1. Writing to registers is performed in the T3 state of a TCNTV write cycle. If a TCNTV clear signal is generated in the T3 state of a TCNTV write cycle, as shown in figure 10.11, clearing takes precedence and the write to the counter is not carried out. If counting-up is generated in the T3 state of a TCNTV write cycle, writing takes precedence.
2. If a compare match is generated in the T3 state of a TCORA or TCORB write cycle, the write to TCORA or TCORB takes precedence and the compare match signal is inhibited. Figure 10.12 shows the timing.
3. If compare matches A and B occur simultaneously, any conflict between the output selections for compare match A and compare match B is resolved by the following priority: toggle output > output 1 > output 0.
4. Depending on the timing, TCNTV may be incremented by a switch between different internal clock sources. When TCNTV is internally clocked, an increment pulse is generated from the falling edge of an internal clock signal, that is divided system clock (ϕ). Therefore, as shown in figure 10.3 the switch is from a high clock signal to a low clock signal, the switchover is seen as a falling edge, causing TCNTV to increment. TCNTV can also be incremented by a switch between internal and external clocks.

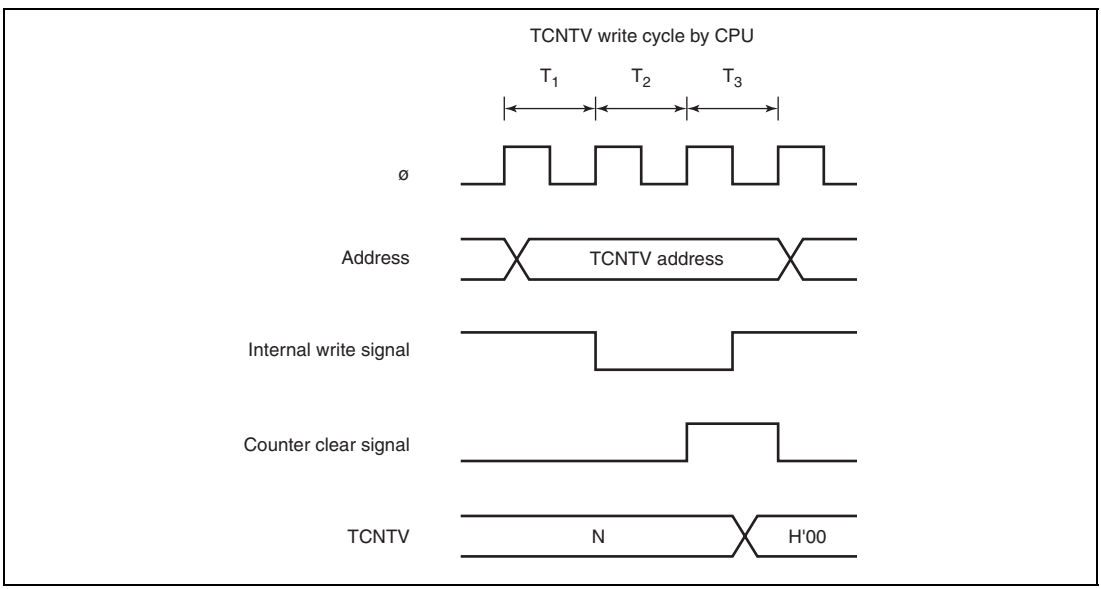


Figure 10.11 Contention between TCNTV Write and Clear

13.8.4 Receive Data Sampling Timing and Reception Margin in Asynchronous Mode

In asynchronous mode, the SCI3 operates on a basic clock with a frequency of 16 times the transfer rate. In reception, the SCI3 samples the falling edge of the start bit using the basic clock, and performs internal synchronization. Receive data is latched internally at the rising edge of the 8th pulse of the basic clock as shown in figure 13.19. Thus, the reception margin in asynchronous mode is given by formula (1) below.

$$M = \left\{ (0.5 - \frac{1}{2N}) - \frac{D - 0.5}{N} - (L - 0.5)\,F \right\} \times 100(\%)$$

... Formula (1)

[Legend\
N: Ratio of bit rate to clock (N = 16)
D: Clock duty (D = 0.5 to 1.0)
L: Frame length (L = 9 to 12)
F: Absolute value of clock rate deviation

Assuming values of F (absolute value of clock rate deviation) = 0 and D (clock duty) = 0.5 in formula (1), the reception margin can be given by the formula.

$$M = \{0.5 - 1/(2 \times 16)\} \times 100\ [\%] = 46.875\%$$

However, this is only the computed value, and a margin of 20% to 30% should be allowed for in system design.

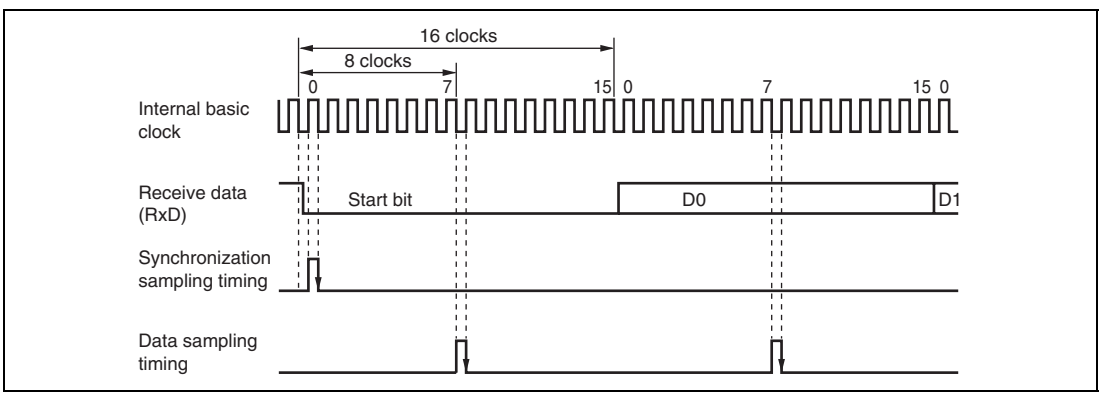
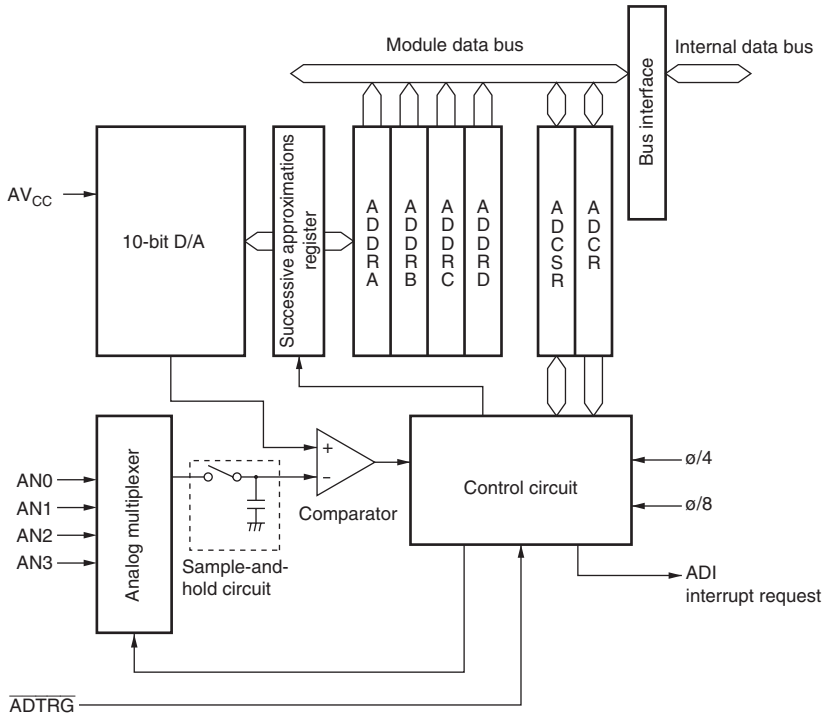


Figure 13.19 Receive Data Sampling Timing in Asynchronous Mode



Legend

ADCR : A/D control register
ADCSR : A/D control/status register
ADDRA : A/D data register A
ADDRB : A/D data register B
ADDRC : A/D data register C
ADDRD : A/D data register D

Figure 14.1 Block Diagram of A/D Converter

14.3.2 A/D Control/Status Register (ADCSR)

ADCSR consists of the control bits and conversion end status bits of the A/D converter.

Bit	Bit Name	Initial Value	R/W	Description
7	ADF	0	R/W	A/D End Flag [Setting conditions] • When A/D conversion ends in single mode • When A/D conversion ends on all the channels selected in scan mode [Clearing conditions] • When 0 is written after reading ADF = 1
6	ADIE	0	R/W	A/D Interrupt Enable A/D conversion end interrupt (ADI) request enabled by ADF when 1 is set
5	ADST	0	R/W	A/D Start Setting this bit to 1 starts A/D conversion. In single mode, this bit is cleared to 0 automatically when conversion on the specified channel is complete. In scan mode, conversion continues sequentially on the specified channels until this bit is cleared to 0 by software, a reset, or a transition to standby mode.
4	SCAN	0	R/W	Scan Mode Selects single mode or scan mode as the A/D conversion operating mode. 0: Single mode 1: Scan mode
3	CKS	0	R/W	Clock Select Selects the A/D conversions time 0: Conversion time = 134 states (max.) 1: Conversion time = 70 states (max.) Clear the ADST bit to 0 before switching the conversion time.

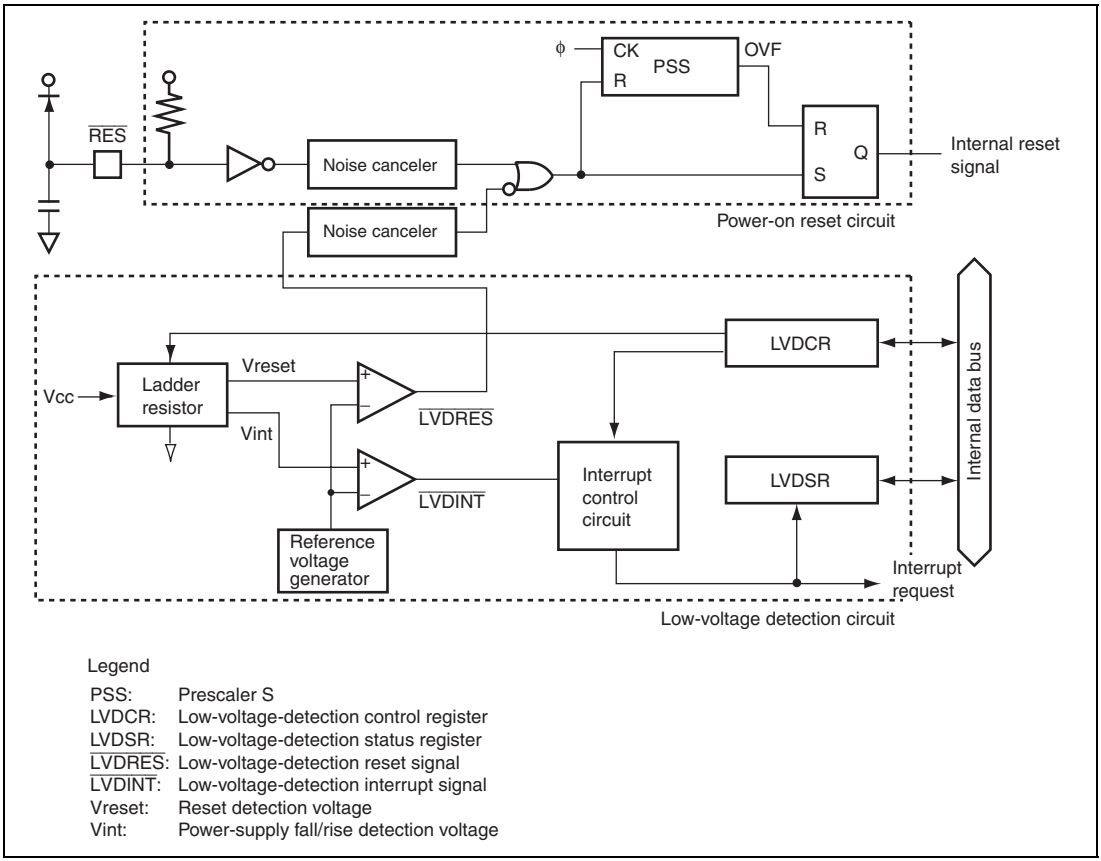


Figure 15.1 Block Diagram of Power-On Reset Circuit and Low-Voltage Detection Circuit

15.2 Register Descriptions

The low-voltage detection circuit has the following registers.

- Low-voltage-detection control register (LVDCR)
- Low-voltage-detection status register (LVDSR)

16.2 When Not Using Internal Power Supply Step-Down Circuit

When the internal power supply step-down circuit is not used, connect the external power supply to the V_{CL} pin and V_{CC} pin, as shown in figure 16.2. The external power supply is then input directly to the internal power supply. The permissible range for the power supply voltage is 3.0 V to 3.6 V. Operation cannot be guaranteed if a voltage outside this range (less than 3.0 V or more than 3.6 V) is input.

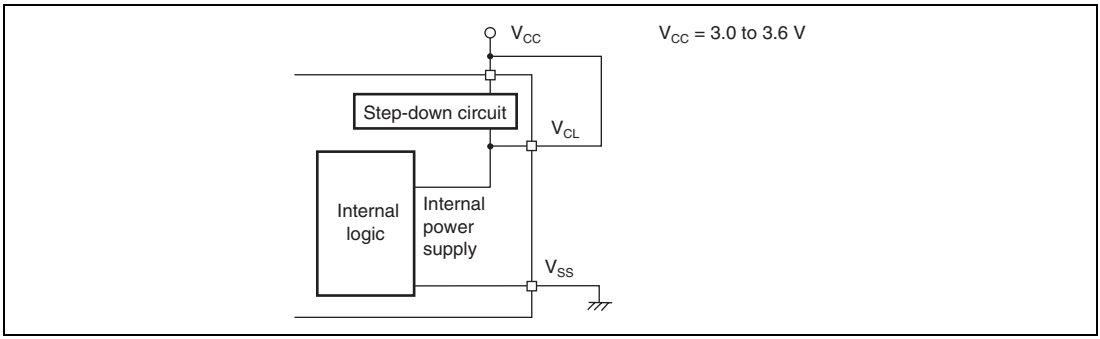


Figure 16.2 Power Supply Connection when Internal Step-Down Circuit is Not Used

17.3 Register States in Each Operating Mode

Register Name	Reset	Active	Sleep	Subsleep	Standby	Module
SMR_3	Initialized	—	—	Initialized	Initialized	SCI3_3
BRR_3	Initialized	—	—	Initialized	Initialized	
SCR3_3	Initialized	—	—	Initialized	Initialized	
TDR_3	Initialized	—	—	Initialized	Initialized	
SSR_3	Initialized	—	—	Initialized	Initialized	
RDR_3	Initialized	—	—	Initialized	Initialized	
SMCR	Initialized	—	—	Initialized	Initialized	
LVDCR	Initialized	—	—	—	—	LVDC (optional)
LVDSR	Initialized	—	—	—	—	
SMR_2	Initialized	—	—	Initialized	Initialized	SCI3_2
BRR_2	Initialized	—	—	Initialized	Initialized	
SCR3_2	Initialized	—	—	Initialized	Initialized	
TDR_2	Initialized	—	—	Initialized	Initialized	
SSR_2	Initialized	—	—	Initialized	Initialized	
RDR_2	Initialized	—	—	Initialized	Initialized	
TMRW	Initialized	—	—	—	—	Timer W
TCRW	Initialized	—	—	—	—	
TIERW	Initialized	—	—	—	—	
TSRW	Initialized	—	—	—	—	
TIOR0	Initialized	—	—	—	—	
TIOR1	Initialized	—	—	—	—	
TCNT	Initialized	—	—	—	—	
GRA	Initialized	—	—	—	—	
GRB	Initialized	—	—	—	—	
GRC	Initialized	—	—	—	—	
GRD	Initialized	—	—	—	—	
FLMCR1	Initialized	—	—	Initialized	Initialized	ROM
FLMCR2	Initialized	—	—	—	—	
EBR1	Initialized	—	—	Initialized	Initialized	
FENR	Initialized	—	—	—	—	

(4) Range of Power Supply Voltage and Oscillation Frequency when Low-Voltage Detection Circuit is Used

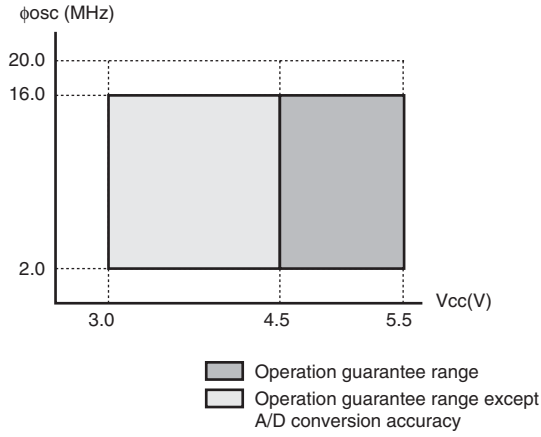


Table 18.4 Serial Interface (SCI3) Timing

V_{CC} = 3.0 V to 5.5 V, V_{SS} = 0.0 V, T_a = –20°C to +75°C, unless otherwise specified.

Item		Symbol	Applicable Pins	Test Condition	Values Min	Typ	Max	Unit	Reference Figure
Input clock cycle	Asynchronous	t_{Scyc}	SCK3, SCK3_2, SCK3_3*		4	—	—	t_{cyc}	Figure 18.4
	Clocked synchronous				6	—	—	t_{cyc}	
Input clock pulse width		t_{SCKW}	SCK3, SCK3_2, SCK3_3*		0.4	—	0.6	t_{Scyc}	
Transmit data delay time (clocked synchronous)		t_{TXD}	TXD, TXD_2, TXD_3*	V_{CC} = 4.0 V to 5.5 V	—	—	1	t_{cyc}	Figure 18.5
					—	—	1	t_{cyc}	
Receive data setup time (clocked synchronous)		t_{RXS}	RXD, RXD_2, RXD_3*	V_{CC} = 4.0 V to 5.5 V	50.0	—	—	ns	
					100.0	—	—	ns	
Receive data hold time (clocked synchronous)		t_{RXH}	RXD, RXD_2, RXD_3*	V_{CC} = 4.0 V to 5.5 V	50.0	—	—	ns	
					100.0	—	—	ns	

Note: * The SCK3_3, RXD_3, and TXD_3 pins are not available in the H8/36014.

18.2.7 Power-Supply-Voltage Detection Circuit Characteristics (Optional)

Table 18.8 Power-Supply-Voltage Detection Circuit Characteristics

V_{SS} = 0.0 V, T_a = –20 to +75°C, unless otherwise indicated.

Item	Symbol	Test Condition	Values			Unit
			Min	Typ	Max	
Power-supply falling detection voltage	Vint (D)	LVDSEL = 0	3.3	3.7	—	V
Power-supply rising detection voltage	Vint (U)	LVDSEL = 0	—	4.0	4.5	V
Reset detection voltage 1*[1]	Vreset1	LVDSEL = 0	—	2.3	2.7	V
Reset detection voltage 2*[2]	Vreset2	LVDSEL = 1	3.0	3.6	4.2	V
Lower-limit voltage of LVDR operation*[3]	$V_{LVDRmin}$		1.0	—	—	V
LVD stabilization time	t_{LVDON}		50	—	—	µs
Current consumption in standby mode	I_{STBY}	LVDE = 1, Vcc = 5.0 V, When a 32-kHz crystal resonator is not used	—	—	350	µA

Notes: 1. This voltage should be used when the falling and rising voltage detection function is used.
2. Select the low-voltage reset 2 when only the low-voltage detection reset is used.
3. When the power-supply voltage (Vcc) falls below $V_{LVDRmin}$ = 1.0 V and then rises, a reset may not occur. Therefore sufficient evaluation is required.

A.3 Number of Execution States

The status of execution for each instruction of the H8/300H CPU and the method of calculating the number of states required for instruction execution are shown below. Table A.4 shows the number of cycles of each type occurring in each instruction, such as instruction fetch and data read/write. Table A.3 shows the number of states required for each cycle. The total number of states required for execution of an instruction can be calculated by the following expression:

$$\text{Execution states} = I \times S_I + J \times S_J + K \times S_K + L \times S_L + M \times S_M + N \times S_N$$

Examples: When instruction is fetched from on-chip ROM, and an on-chip RAM is accessed.

BSET #0, @FF00

From table A.4:
I = L = 2, J = K = M = N= 0

From table A.3:
$S_I = 2$, $S_L = 2$

Number of states required for execution = $2 \times 2 + 2 \times 2 = 8$

When instruction is fetched from on-chip ROM, branch address is read from on-chip ROM, and on-chip RAM is used for stack area.

JSR @@ 30

From table A.4:
I = 2, J = K = 1, L = M = N = 0

From table A.3:
$S_I = S_J = S_K = 2$

Number of states required for execution = $2 \times 2 + 1 \times 2 + 1 \times 2 = 8$

Instruction	Mnemonic	Instruction Fetch I	Branch Addr. Read J	Stack Operation K	Byte Data Access L	Word Data Access M	Internal Operation N
ROTXR	ROTXR.B Rd	1					
	ROTXR.W Rd	1					
	ROTXR.L ERd	1					
RTE	RTE	2		2			2
RTS	RTS	2		1			2
SHAL	SHAL.B Rd	1					
	SHAL.W Rd	1					
	SHAL.L ERd	1					
SHAR	SHAR.B Rd	1					
	SHAR.W Rd	1					
	SHAR.L ERd	1					
SHLL	SHLL.B Rd	1					
	SHLL.W Rd	1					
	SHLL.L ERd	1					
SHLR	SHLR.B Rd	1					
	SHLR.W Rd	1					
	SHLR.L ERd	1					
SLEEP	SLEEP	1					
STC	STC CCR, Rd	1					
	STC CCR, @ERd	2				1	
	STC CCR, @(d:16,ERd)	3				1	
	STC CCR, @(d:24,ERd)	5				1	
	STC CCR,@-ERd	2				1	2
	STC CCR, @aa:16	3				1	
	STC CCR, @aa:24	4				1	
SUB	SUB.B Rs, Rd	1					
	SUB.W #xx:16, Rd	2					
	SUB.W Rs, Rd	1					
	SUB.L #xx:32, ERd	3					
	SUB.L ERs, ERd	1					
SUBS	SUBS #1/2/4, ERd	1					

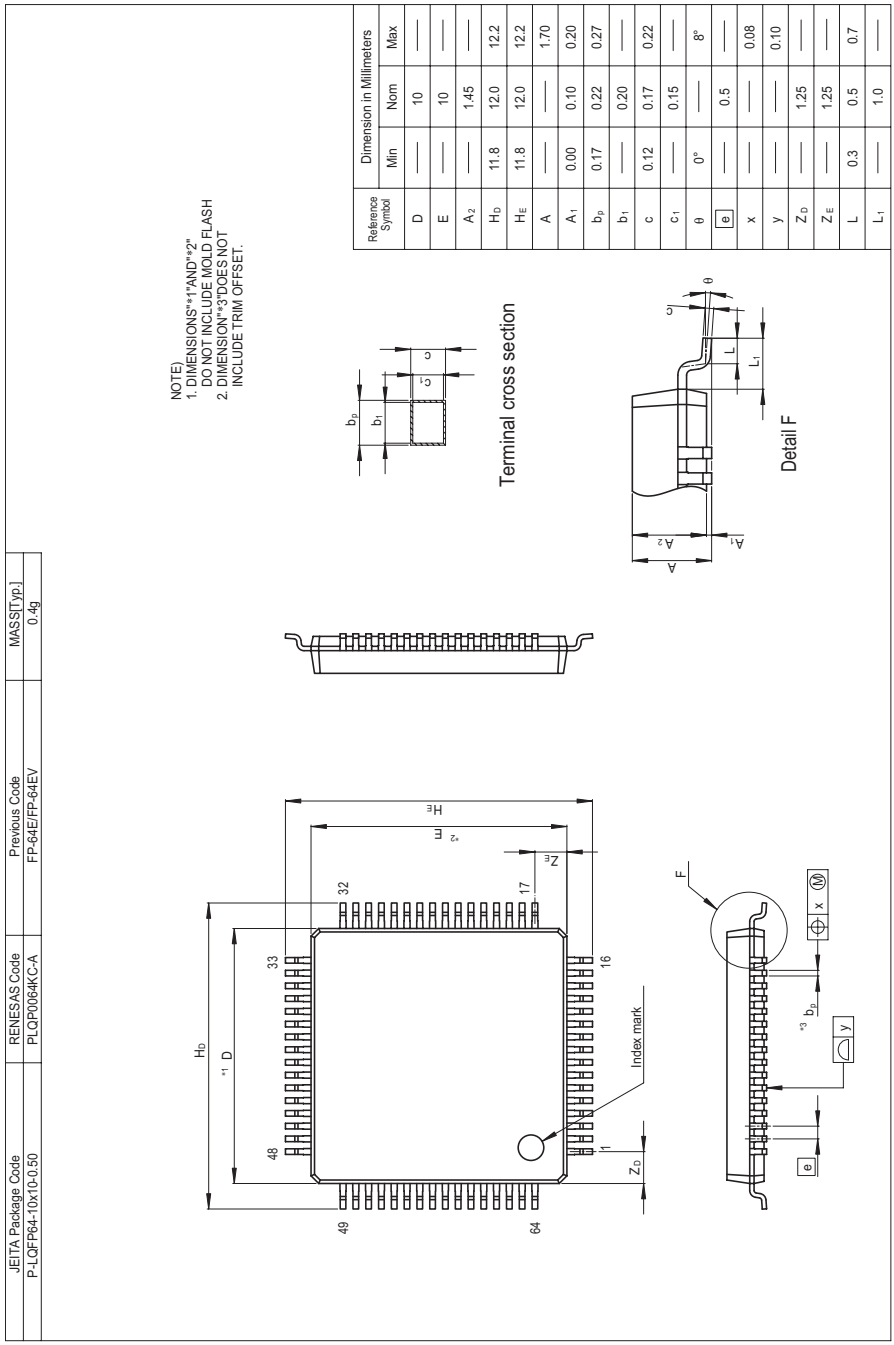


Figure D.1 FP-64E Package Dimensions